



Technical Data Sheet S-Bond Deck  
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# S-Bond Deck

## One-part SiMP deck flooring adhesive

### DESCRIPTION

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S-Bond Deck is a ready-to-use, one-component, deck flooring SiMP – Silyl Modified Polymer adhesive. Specifically formulated for bonding teak slats to marine plywood, fiberglass reinforced plastic, wood, aluminum and steel. It offers an effective long-term resistance to fresh water, sea water, diluted aqueous cleansing agents. The product does not contain isocyanates, is solvent- and water-free, does not shrink during the curing phase and provides a permanent bond between large substrates.

### AREAS OF APPLICATION

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S-Bond Deck is specific for bonding marine decks to supporting structures. Particularly formulated for bonding of teak slats to marine plywood, fiber glass reinforced plastic, wood, aluminum and steel.

### FEATURES

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- SiMP Silyl-Modified Polymer
- Ready-to-use, no mixing required
- Solvent and isocyanate free, odourless
- Fast curing with possibility to be combined to a booster
- No bulging or bubbling effect
- Easy to spread and trowel by spatula
- Easy to remove from hands and from parquet surface
- No Hazard symbol required
- Long term resistance to fresh water, sea water, diluted aqueous cleansing agents



## TECHNICAL DATA

<b>Appearance</b>	Thixotropic paste
<b>Color</b>	Black
<b>Chemical nature</b>	SiMP – Silyl Modified Polymer
<b>Curing Mechanism</b>	Moisture-curing
<b>Density</b> [g/cm <sup>3</sup> ] (NPT method 06) (23°C and 50% RH)	ca. 1.61
<b>Shore A hardness</b> (DIN 53505)	ca. 70
<b>Skin time</b> [min] (NPT Method 17) (23°C and 50% RH)	ca. 55
<b>Curing through volume</b> [mm] (NPT Method 07) (23°C and 50% RH)	ca. 2.5
<b>Full curing when used with 15% booster</b> [h] (23°C and 50% RH)	ca. 24
<b>Tensile strength</b> [N/mm <sup>2</sup> ] (ISO 37 DIN 53504)	ca. 2.5
<b>Elongation at break</b> [%] (ISO 37 DIN 53504)	ca. 100
<b>Application temperature</b> [°C]	From +5 to +40
<b>Plank setting time</b> [h]	ca. 1
<b>Sandpapering</b> [days]	ca. 3
<b>Operative temperature</b> [°C]	From -10 to +60
<b>Temperature Resistance</b> [°C]	From -40 to +90

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## APPLICATION

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Verify that the temperature during the application is between 5°C and 40°C. In order to guarantee a perfect and durable bonding, an accurate cleaning of the substrates which are to be bonded is necessary. Consequently, the substrates must be dry, clean and free from dust, grease, oils and corrosion. Degreasing the substrates with acetate is advisable; wait for their complete evaporation.

Steel and Aluminum boat decks: A preliminary treatment of the metal surface with epoxy or polyurethane primers as protective coatings in order to avoid potential corrosion is required. Preliminary adhesion tests are advised in order to verify the perfect adhesion of S-Bond Deck.

Gel coat, wood (marine plywood) boat decking: a light sanding abrasion and cleaning with acetate is required for the removal of any surface contaminants; wait for their complete evaporation.

Treat the base of the teak staves with the U-Primer 199DC. After 120 minutes and not more 24h from the application of the U-Primer 199DC apply the S-Bond Deck.

Apply the adhesive with a trowel onto the boat deck using a toothed spatula (5mm teeth) making sure to create a homogeneous layer of maximum 3mm between the deck and the plywood or between the plywood and the teak staves. The layer must be applied in order to evenly fill the spaces between the substrates. This operation is important in order to avoid any infiltration of water from the deck.

Within 30 minutes apply the teak staves which are to be bonded.

On application of both the plywood and teak staves, it is necessary that the deck and the wood substrates adhere perfectly. This is possible in the following ways:

- By a mechanical fixing (temporary)
- Guaranteeing the adhesion of the substrates by applying pressure using weighs or clamps
- With a vacuum-packed system

With respect to the last two methods, it is important that the pressure applied is sufficient to guarantee a correct adhesion of the substrates and that the contact between them is maintained as long as necessary to complete the curing of the S-Bond DECK.

The boat deck can be successfully sealed with SiMP-Seal Teak once the S-Bond Deck curing is complete (approx 48-72 hours).

It is possible to combine S-Bond Deck with NPT booster mixing at a ratio of 5% to 15% in weight. S-Bond Deck will cure within its mass, reaching full curing in about 24h.

## CLEANING OF EQUIPMENT AND PERSONAL PROTECTIVE MEASURES

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Clean the tools used with acetone or solvent. When the adhesive has not yet hardened, it can be removed using paper or a cloth. Once hardened, the product can only be removed mechanically. Avoid skin contact by using latex, rubber or polyethylene gloves. If it comes in contact with the skin, remove immediately and wash with soap and water.



## PACKAGING

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Foilbag 7 kg - 2 pieces in a pail

## STORAGE AND SHELF LIFE

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S-Bond Deck can be stored for 12 months in its original packaging (unopened container) between 10°C and 25°C in a cool, dry place. The storage temperature should not exceed 25°C for extended periods of time. Keep away from wet areas, direct sunlight and heat sources.

## GENERAL INFORMATION

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The information contained in this technical data sheet is to the best of our knowledge correct, being based on our knowledge and experience to date and cannot be used as a guarantee, due to the various different materials present on the market and the fact that the application conditions are not under our direct control and supervision. NPT srl, however, guarantees constant product quality. NPT srl, has the right to modify or up-date this technical data sheet according to requirements. Customers are kindly requested to verify that they are in possession of the latest version.

ALWAYS CONSULT THE MATERIAL SAFETY DATA SHEET BEFORE USING THE PRODUCT